

IN THE CLAIMS:

Please add claims 21-25 and amend the remaining claims as follows:

1. (Currently Amended) An integrated circuit structure comprising:
 - an insulator layer;
 - a pad comprising a conductive material on said insulator layer, said pad having a wirebond connection region and a probe pad region; and
 - an inspection mark between said wirebond connection region and said probe pad region, wherein said inspection mark comprises an opening in said insulator layer that is filled with said conductive material, and
wherein said probe pad region is adapted to make physical contact with a probe.
2. (Original) The structure in claim 1, further comprising a polyimide layer above said conductive material, said polyimide having a second opening, wherein said pad is exposed through said second opening.
3. (Original) The structure in claim 1, wherein said inspection mark opening is formed above an insulating region of said wiring layer.
4. (Original) The structure in claim 1, wherein said conductor comprises a refractory metal.

5. (Original) The structure in claim 1, wherein said conductor comprises one of aluminum, tantalum, titanium, and alloys thereof.

6. (Original) The structure in claim 1, wherein said inspection mark is visible from an exterior of said integrated circuit structure.

7. (Original) The structure in claim 1, wherein said inspection mark delineates where probe inspection marks are permitted on said pad.

8. (Currently Amended) An integrated circuit structure comprising:
a wiring layer below said insulator layer said wiring layer comprising a conductor wire;
an insulator layer on said wiring layer;
a pad comprising a conductive material on said insulator layer, said pad having a wirebond connection region and a probe pad region;
an inspection mark between said wirebond connection region and said probe pad region, wherein said inspection mark comprises an opening in said insulator layer that is filled with said conductive material, and wherein said probe pad region is adapted to make physical contact with a probe; and

a contact through said insulator layer, said contact being adapted to electrically connect said conductor wire in said wiring layer to said pad, wherein said contact comprises said conductive material.

9. (Original) The structure in claim 8, further comprising a polyimide layer above said conductive material, said polyimide having a second opening, wherein said pad is exposed through said second opening.

10. (Original) The structure in claim 8, wherein said inspection mark opening is formed above an insulating region of said wiring layer.

11. (Original) The structure in claim 8, wherein said conductor comprises a refractory metal.

12. (Original) The structure in claim 8, wherein said conductor comprises one of aluminum, tantalum, titanium, and alloys thereof.

13. (Original) The structure in claim 8, wherein said inspection mark is visible from an exterior of said integrated circuit structure.

14. (Original) The structure in claim 8, wherein said inspection mark delineates where probe inspection marks are permitted on said pad.

15 – 20. (Cancelled).

21. (New) An integrated circuit structure comprising:

a wiring layer below said insulator layer said wiring layer comprising a conductor wire;
an insulator layer on said wiring layer;
a pad comprising a conductive material on said insulator layer, said pad having a
wirebond connection region and a probe pad region;
an inspection mark between said wirebond connection region and said probe pad region,
wherein said inspection mark comprises an opening in said insulator layer that is filled
with said conductive material,
wherein said inspection mark is visible from an exterior of said integrated circuit
structure,
wherein said inspection mark delineates where probe inspection marks are permitted on
said pad, and
wherein said probe pad region is adapted to make physical contact with a probe; and
a contact through said insulator layer, said contact being adapted to electrically connect
said conductor wire in said wiring layer to said pad, wherein said contact comprises said
conductive material.

22. (New) The structure in claim 8, further comprising a polyimide layer above said
conductive material, said polyimide having a second opening, wherein said pad is exposed
through said second opening.

23. (New) The structure in claim 8, wherein said inspection mark opening is formed above an
insulating region of said wiring layer.

24. (New) The structure in claim 8, wherein said conductor comprises a refractory metal.

25. (New) The structure in claim 8, wherein said conductor comprises one of aluminum, tantalum, titanium, and alloys thereof.